

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DANIEL E. KILLIAN	09/24/2019
SIVARAM BALASUBRAMANIAN	09/25/2019
KENDAL R. HARRIS	09/25/2019
CHANDRESH R. CHAUDHARI	09/25/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ROCKWELL AUTOMATION TECHNOLOGIES, INC.
<b>Street Address:</b>	1 ALLEN-BRADLEY DRIVE
<b>City:</b>	MAYFIELD HEIGHTS
<b>State/Country:</b>	OHIO
<b>Postal Code:</b>	44124
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16584194
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(216)363-9001
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	414-382-4946
<b>Email:</b>	CSCHWETER@FAYSHARPE.COM
<b>Correspondent Name:</b>	ROCKWELL AUTOMATION, INC./FAY SHARPE LLP
<b>Address Line 1:</b>	1201 SOUTH SECOND STREET
<b>Address Line 4:</b>	MILWAUKEE, WISCONSIN 53204
<b>ATTORNEY DOCKET NUMBER:</b>	ROKZ 200222US01
<b>NAME OF SUBMITTER:</b>	STEVEN HAAS
<b>SIGNATURE:</b>	/Steven Haas/
<b>DATE SIGNED:</b>	10/02/2019
<b>Total Attachments: 8</b>	
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**2019P-081-US - ASSIGNMENT BY INVENTORS**

DANIEL E. KILLIAN, SIVARAM BALASUBRAMANIAN,  
KENDAL R. HARRIS and CHANDRESH R. CHAUDHARI

(Inventors) have invented

**DISTRIBUTED MODULAR INPUT/OUTPUT (I/O) SYSTEM WITH  
REDUNDANT ETHERNET BACKPLANE NETWORKS FOR IMPROVED  
FAULT TOLERANCE**

(the Inventions), as described in:

U.S. Patent Application Ser. No. 16/584,194, filed September 26, 2019 (the Application).

Rockwell Automation Technologies, Inc. (Assignee), an Ohio Corporation with a principal place of business at 1 Allen-Bradley Drive, Mayfield Heights, Ohio 44124, is desirous of acquiring the entire right, title, and interest in the Inventions and the Application. Any reference in this assignment to the Assignee encompasses the successors, legal representatives, and assigns of the Assignee.

For good and sufficient consideration, the receipt of which is hereby acknowledged, Inventors hereby transfer to Assignee the entire right, title, and interest in the Inventions and the Application, and in all patents and patent applications covering the Inventions or resulting from the Application, including all provisional, non-provisional, continuation, continuation-in-part, divisional, reissue, reexamination, foreign, and PCT applications, and any patents resulting from these applications, in the United States and in all foreign countries, including in particular the rights of priority originating from the Application.

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Inventors hereby authorize the Director of the U.S. Patent and Trademark Office and the empowered officials of all other governments to issue all patents covering the Inventions or resulting from the Application, to the Assignee.

Inventors hereby agree to carry out in good faith the intent and purpose of this assignment; to communicate to Assignee any facts relating to the Inventions, the Application, and any patents and applications that cover the Inventions or result from

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The Inventors executed this assignment as of the dates indicated below:

Date: 09/24/2019

*Daniel E Killian*

Daniel E Killian (Sep 24, 2019)

**DANIEL E. KILLIAN**

Date: \_\_\_\_\_

**SIVARAM BALASUBRAMANIAN**

Date: \_\_\_\_\_

**KENDAL R. HARRIS**

Date: \_\_\_\_\_

**CHANDRESH R. CHAUDHARI**

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**DANIEL E. KILLIAN**

Date: 09/25/2019  
\_\_\_\_\_

*Sivaram Balasubramanian*  
Sivaram Balasubramanian (Sep 25, 2019)

\_\_\_\_\_  
**SIVARAM BALASUBRAMANIAN**

Date: \_\_\_\_\_

\_\_\_\_\_  
**KENDAL R. HARRIS**

Date: \_\_\_\_\_

\_\_\_\_\_  
**CHANDRESH R. CHAUDHARI**

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**DANIEL E. KILLIAN**

Date: \_\_\_\_\_

\_\_\_\_\_  
**SIVARAM BALASUBRAMANIAN**

Date: 09/25/2019

*Kendal R. Harris*

Kendal R. Harris (Sep 25, 2019)

\_\_\_\_\_  
**KENDAL R. HARRIS**

Date: \_\_\_\_\_

\_\_\_\_\_  
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**SIVARAM BALASUBRAMANIAN**

Date: \_\_\_\_\_

\_\_\_\_\_  
**KENDAL R. HARRIS**

*Chandresh R. Chaudhari*

Chandresh R. Chaudhari (Sep 25, 2019)

Date: 09/25/2019

\_\_\_\_\_  
**CHANDRESH R. CHAUDHARI**